

Title (en)

Method for installing a floor covering on a floor

Title (de)

Verfahren zum Anbringen eines Bodenbelages auf einen Boden

Title (fr)

Procédé destiné à l'application d'un revêtement de sol sur un sol

Publication

**EP 1953308 A1 20080806 (DE)**

Application

**EP 07101506 A 20070131**

Priority

EP 07101506 A 20070131

Abstract (en)

The method involves introducing slits into an old floor covering (2), and introducing glue (5) e.g. SikaBond-T52 (RTM: wood flooring glue), into the slits. A new floor covering (6) e.g. carpet, is superimposed on the slits and bonded with floor (1) by an adhesive layer (3). The slits are applied on the floor, and a mat is arranged between the old and new floor coverings. The mat is applied before the glue is applied into the slits.

Abstract (de)

Bei einem Verfahren zum Anbringen eines Bodenbelages (6) auf einen Boden (1), werden Schlitze (4) in den alten Bodenbelag (2) eingebracht, Klebstoff (5) wird in die Schlitze (4) eingebracht, der neue Bodenbelag (6) aufgebracht und der neue Bodenbelage (6) mit dem Boden (1) verklebt.

IPC 8 full level

**E04F 15/02** (2006.01)

CPC (source: EP US)

**E04F 15/02** (2013.01 - EP US); **E04F 15/0215** (2013.01 - EP US); **E04F 15/20** (2013.01 - EP US)

Citation (search report)

- [X] DE 10253553 A1 20031002 - KATTWINKEL FRIEDER [DE]
- [X] WO 9949152 A1 19990930 - CASA DA VINCI BODENSYSTEME GMB [DE], et al
- [A] EP 0182567 A2 19860528 - PLASMOR INSULATION LTD [GB]
- [AX] DE 19755626 A1 19990617 - ESSER RUDOLF [DE]
- [A] WO 0240806 A2 20020523 - LU ERIC CHIA CHUN [US], et al
- [A] WO 02088486 A1 20021107 - ABRAHAMS JACOB [BR], et al
- [A] DE 9213604 U1 19930325
- [A] US 2002071931 A1 20020613 - DRAKE ROBERT H [US]
- [A] NL 1028415 C2 20060403 - BOLIDT MIJ TOT EXPLOITATIE VAN [NL]

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